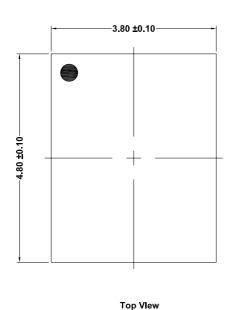
Plastic Packages for Integrated Circuits

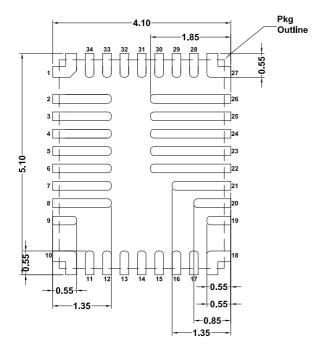
Package Outline Drawing

L34.3.8x4.8

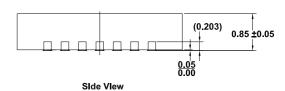
34 Lead Flip Chip Quad Flat No-Lead Package (FCQFN) Rev 0, 11/2021



1.20 ±0.05 (8X)-+1.70 ±0.05 (5X)+ 0.400 ±0.05-29 30 0.40 ±0.05(16X) 27 C0.150X45° 0.40 ±0,05 2 26 25 3 24 23 22 0.40 0.825 (1.0) 0.25 ±0.05 (8X)---0.20 ±0.05 (30X) 0.70 ±0.05 (1X)-**Bottom View**



Typical Recommended Land Pattern



Notes:

- Dimensioning and tolerancing conforms to ASME Y14.5M - 1994.
- 2. All dimensions are in millimeters, Dimensions in () for reference only.